

Ziptronix accuses TSMC / Omnivision of Patent Infringement Over Oxide Bonding Technology

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In question here is the use of oxide bonding for backside illumination in CMOS image sensors (CIS) , if such oxide surfaces are treated with plasma and/or other chemicals and if the Ziptronix patent claims pertaining to these processes are valid.

A recent market study by Yole Développement [see "[2010CMOS Image Sensors Technologies & Markets -2010](#) [1]"] has reported that most of the CIS manufacturers have moved, or are moving, to back side imaging (BSI) technology.

Company	2009 CIS Wafer Production Forecast
	Market share (~%)
TSMC	22
Aptina (Micron)	15
Samsung	15
Canon	10
Sony	8
Toshiba	6
ST Micro	6
UMC	5
Dongbu HiTek	4
Hynix	4

[SOURCE](#) [2]

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http://www.mdtmag.com/news/2011/01/ziptronix-accuses-tsmc/omnivision-patent-infringement-over-oxide-bonding-technology?qt-video_of_the_day=0

Links:

[1] <http://www.i-micronews.com/reports/CMOS-Image-Sensors-Technologies-Markets-2010-Report/126/>

[2] <http://www.i-micronews.com/lectureArticle.asp?id=6100>